



SOT536-1

plastic, low profile fine-pitch ball grid array package; 96 balls;
0.8 mm pitch; 13.5 mm x 5.5 mm x 1.5 mm body

30 January 2017

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA96
Package type industry code	LFBGA96
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	5-2-2003
Manufacturer package code	SOT536

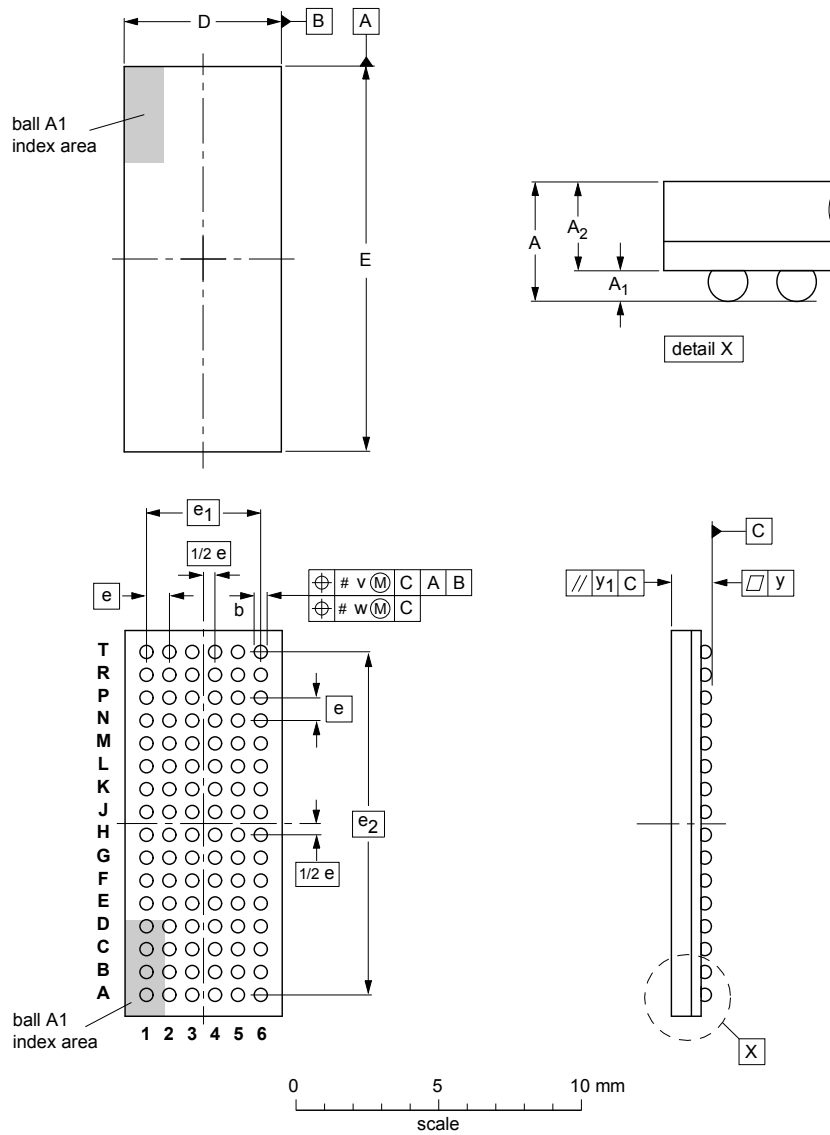
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	13.4	-	13.5	13.6	mm
A	seated height	-	-	1.5	1.5	mm
A ₂	package height	0.9	-	1.05	1.2	mm
e	nominal pitch	-	-	0.8	-	mm
n ₂	actual quantity of termination	-	-	96	-	

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2. Package outline

LFBGA96: plastic low profile fine-pitch ball grid array package; 96 balls; body 13.5 x 5.5 x 1.05 mm SOT536-1



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	1.5	0.41 0.31	1.2 0.9	0.51 0.41	5.6 5.4	13.6 13.4	0.8	4	12	0.15	0.1	0.1	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT536-1						-00-03-04- 03-02-05

Fig. 1. Package outline LFBGA96 (SOT536-1)

plastic, low profile fine-pitch ball grid array package; 96 balls; 0.8 mm pitch; 13.5 mm x 5.5 mm x 1.5 mm body

3. Soldering

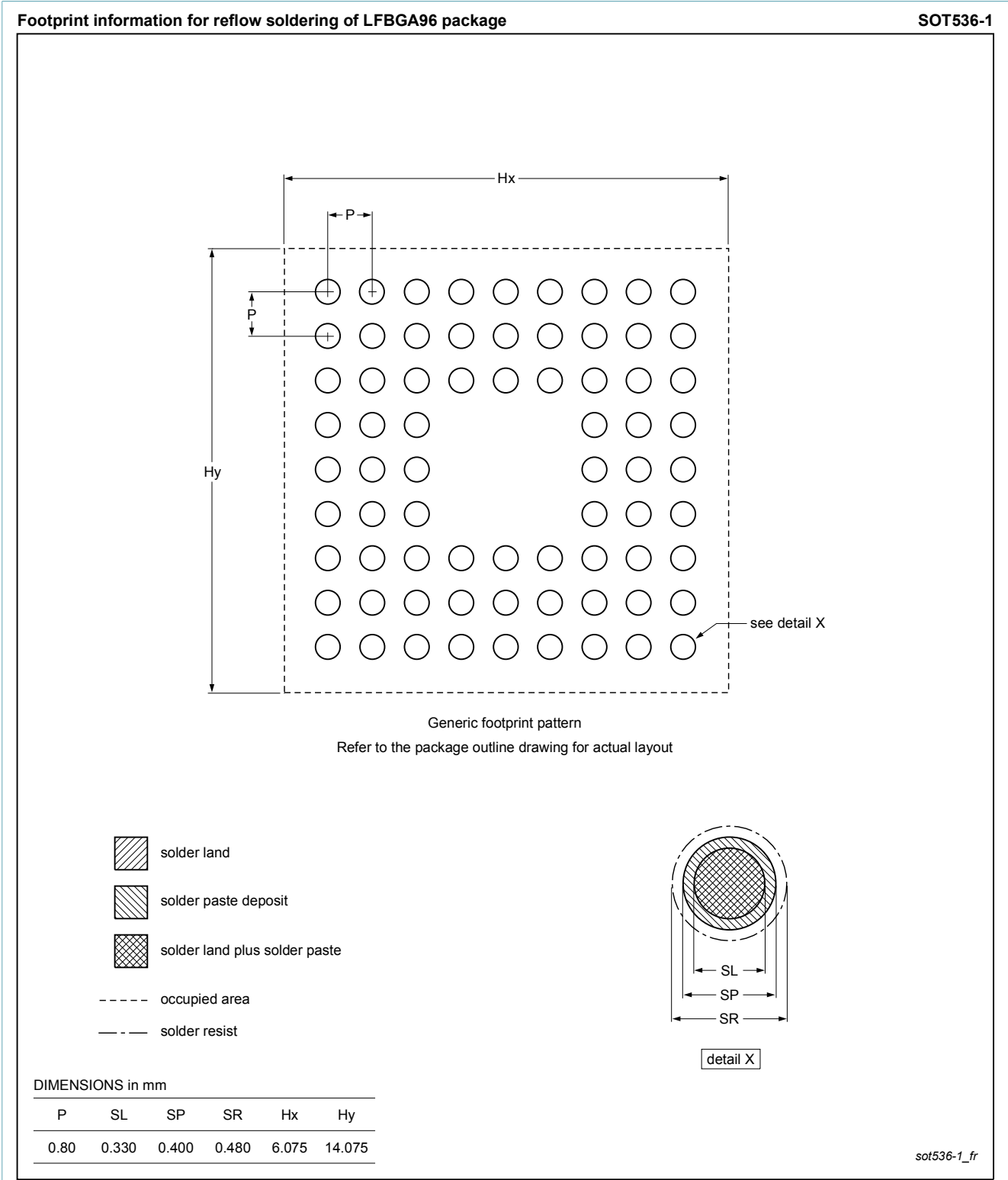


Fig. 2. Reflow soldering footprint for LFBGA96 (SOT536-1)

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body

4. Legal information

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